

REV	ECN No.	DATE	REMARK
A	NEW	2020.11.25	新版发行
B	---	2023.04.23	整理图面
C	---	2024.02.28	增加3U TID No.

NOTE:

- ELECTRICAL PERFORMANCE,
 - CURRENT RATING:5 AMPS. FOR TOTAL VBUS/GND PINS;
1.25AMPS FOR CC PIN,
0.25 AMPS. FOR ALL OTHER CONTACT.
 - VOLTAGE RATING:20V DC/AC (RMS. MAX)
 - CONTACT RESISTANCE: 40MΩ MAX INITIAL.
50MΩ MAX AFTER TEST
 - DIELECTRIC WITHSTANDING VOLTAGE: 100V AC
 - INSULATION RESISTANCE:100MΩ MIN
- MECHANICAL PERFORMANCE,
 - INSERTION FORCE: 5~20N.
 - EXTRACTION FORCE: 8~20N.
 - DURABILITY: 10000 CYCLES.
- ENVIRONMENTAL PERFORMANCE:
 - OPERATING TEMPERATURE: -25°C~+85°C.
- IR REFLOW:
 - THE PEAK TEMPERATURE ON THE BOARD SHALL BE MAINTAINED FOR 10 SECONDS AT 260°C.
- COMPLIANCE WITH ROHS& HF REQUIREMENTS.
- SALT SPRAY:48H

Pin Definition:

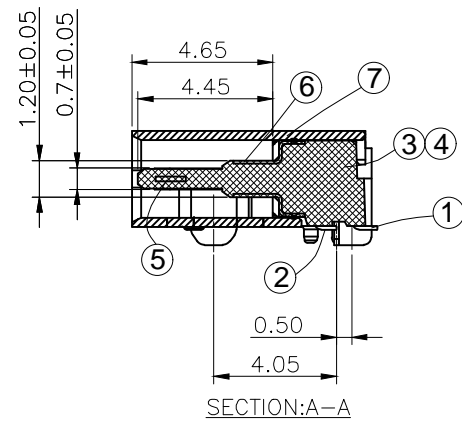
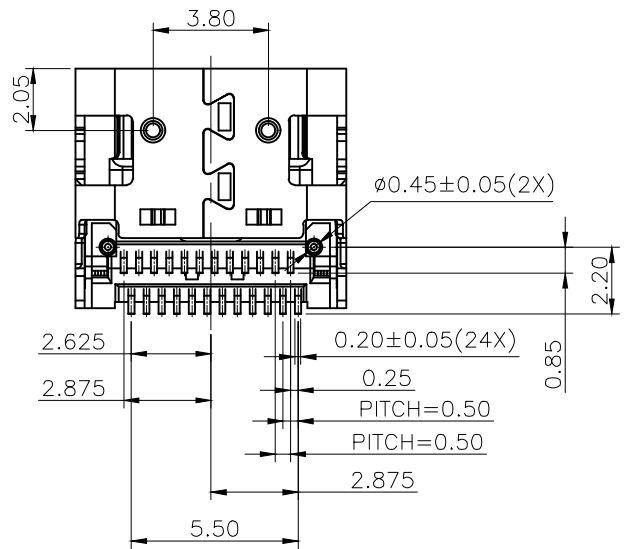
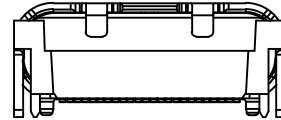
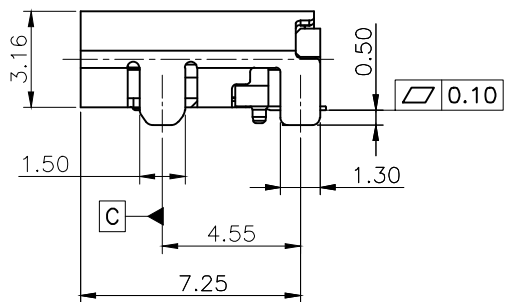
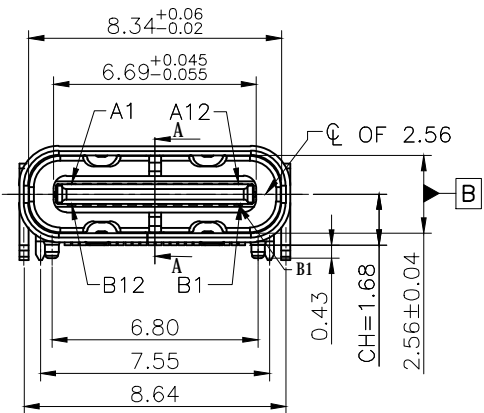
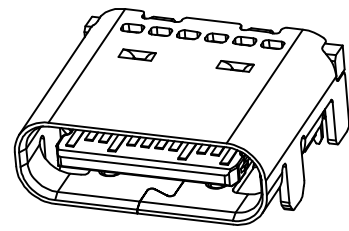
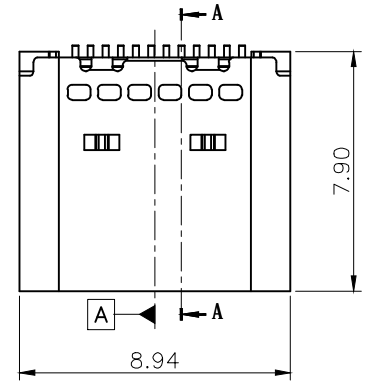
PIN No.	A1	A2	A3	A4	A5	A6	A7	A8	A9	A10	A11	A12
SIGNAL NAME	GND	TX1+	TX1-	VBUS	CC1	D+	D-	SBU1	VBUS	RX2-	RX2+	GND

PIN No.	B12	B11	B10	B9	B8	B7	B6	B5	B4	B3	B2	B1
SIGNAL NAME	GND	RX1+	RX1-	VBUS	SBU2	D-	D+	CC2	VBUS	TX2-	TX2+	GND

TABLE:

7	SHELL	1	SUS304 T=0.30	Ni 30μ" MIN. UNDER PLATED OVER ALL.
6	EMI	1	SUS304 T=0.10	Ni 30μ" MIN. UNDER PLATED OVER ALL.
5	SHIELDING PLATE	1	SUS301 T=0.15	Ni 30μ" MIN. UNDER PLATED OVER ALL. Sn 80μ"MIN. PLATED OVER ALL.
4	INSULATOR 2	1	LCP/PA6T UL94V-0	COLOR:BLACK
3	INSULATOR 1	1	LCP/PA6T UL94V-0	COLOR:BLACK
2	Down CONTACT	12	C18400 T=0.12	Ni 50μ" MIN. UNDER PLATED OVER ALL.
1	TOP CONTACT	12	C18400 T=0.12	Au PLATED ON CONTACT,GF/Sn PLATED ON SOLDERING

GENERAL TOLERANCES (UNLESS SPECIFIED)		DRAWN BY: HuangXiaoHao		Date: 2024.02.28		GOLDCONN TECHNOLOGIES COMPANY LIMITED	
X.XXX	±0.10	CHECKED BY: liuzongliang		Date: 2024.02.28		TITLE	
X.XX	±0.25	APPROVED BY: Jacky		Date: 2024.02.28		USB TYPE-C FEMALE 24PIN TOP-MOUNT DUAL ROW SMT, CH=1.68mm	
X.X	±0.30	THIRD ANGLE PROJECTION		UNT	SCALE	DRAWING	SHEET NO.
ANGULAR	±3'	mm	1:1	A4	1 OF 2	DWG NO.	ED-UC-009

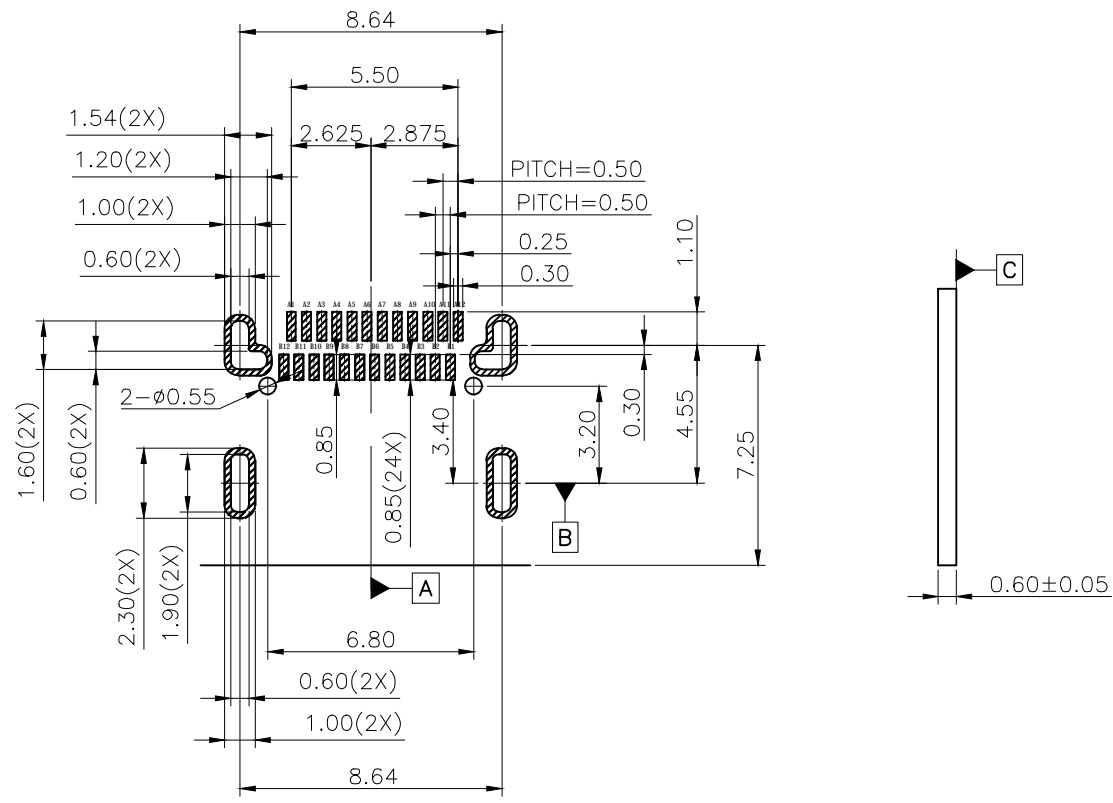


PART NUMBER CODE:

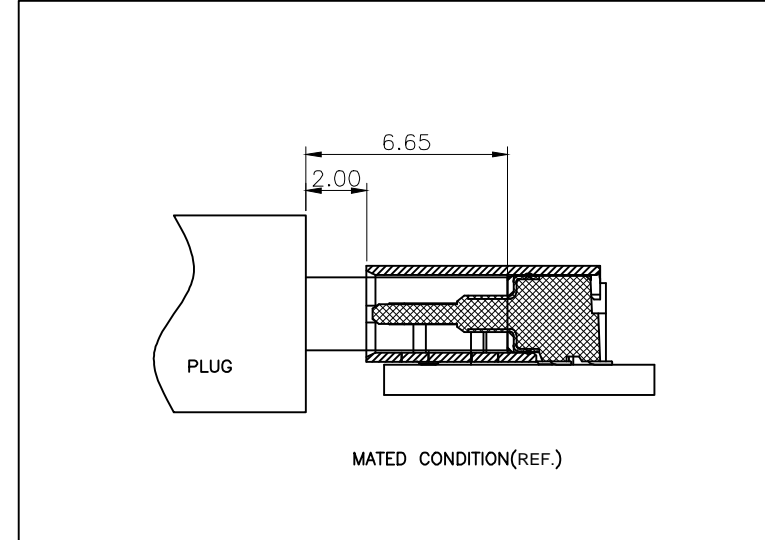
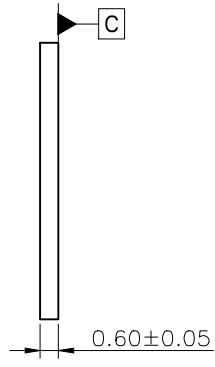


NO.	PART NO.	PLATED	PACKING	TID NO.	IEC62680-1-3
1	USF04-221212-023R	LCP BLACK Contact Area: Au 3u";Solder Tails:GF	TAPE & REEL	10734	24B01N001793-005-COM
2	USF04-221215-023R	LCP BLACK Contact Area: Au 30u";Solder Tails:GF	TAPE & REEL	5200000273	24B01N001456-001-COM
3	USF04-231212-023R	PA9T BLACK Contact Area: Au 3u";Solder Tails:GF	TAPE & REEL	12593	24T04N002786-002-COM
4	USF04-221214-023R	LCP BLACK Contact Area: Au 15u";Solder Tails:GF	TAPE & REEL	----	----
5	USF04-221202-023R	LCP BLACK Contact Area: Au 3u";Solder Tails:Tin	TAPE & REEL	----	----
6	USF04-221212-023VR	LCP BLACK Contact Area: Au 3u";Solder Tails:GF	TAPE & REEL +Vacuum Packaging	----	----

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RECOMMENDED PCB LAYOUT(TOP VIEW)
THICKNESS 0.60MM;DEFAULT TOLERANCE:±0.05



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X.XX	±0.25	APPROVED BY: Jacky		Date: 2024.02.28		USB TYPE-C FEMALE 24PIN TOP-MOUNT DUAL ROW SMT, CH=1.68mm		
X.X	±0.30	THIRD ANGLE PROJECTION		UNT	SCALE	DRAWING	SHEET NO.	DWG NO.
ANGULAR	±3'	mm		1:1	A4	2 OF 2	ED-UC-009	